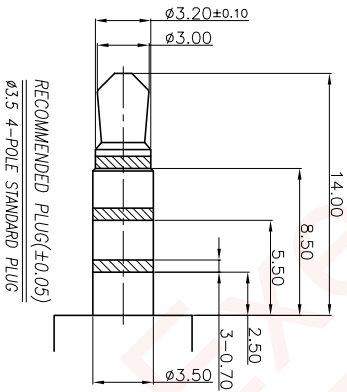
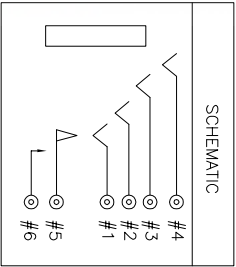
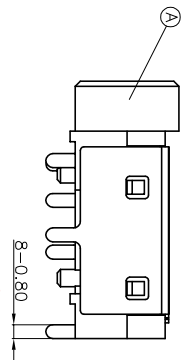
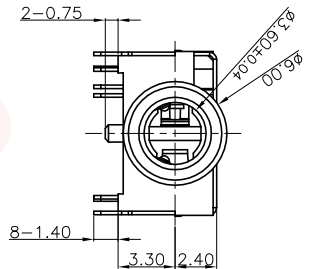
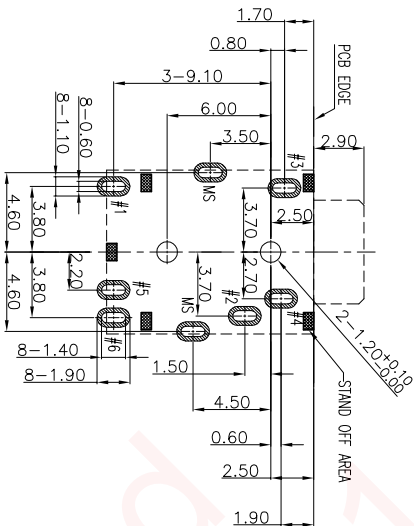




RECOMMENDED PCB LAYOUT(TOP VIEW)
(TOLERANCE: ±0.05)



SPECIFICATIONS:

- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC.
- CONTACT RESISTANCE: 50mΩ MAX.
- INSULATION VOLTAGE WITHSTAND:500V AC FOR ONE MINUTE.
- UNLESS OTHERWISE SPECIFIED TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT,IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
- LIFE TEST: 5,000 CYCLES.
- INSERTION FORCE: 0.3 - 3.0Kg.
- WITHDRAWAL FORCE: 0.3 - 3.0Kg.
- AFTER LIFE TEST, CONTACT RESISTANCE: 100mΩ MAX.
- AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50MΩ MIN.
- MARKING: MARK "S" ON TOP OF CONNECTOR.
- PACKING : TAPE & REEL.
- TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
- HALOGEN FREE PRODUCT IDENTIFICATION MARK ON JACK:
- HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING:

I	SHELL	1	COPPER ALLOY, 0.2t	NICKEL 60μ" MIN. PLATING
H	SEPARATE	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK
G	MAKE TERMINAL	1	COPPER ALLOY, 0.2t	GOLD FLASH ON CONTACT AREA, WHITE TIN 120μ" ON SOLDER TAIL, ALL OVER NICKEL 50μ" MIN. PLATING, GOLD FLASH ON CONTACT AREA, ALL OVER NICKEL 50μ" MIN. PLATING
F	TRANSFER TERMINAL	1	COPPER ALLOY, 0.2t	ALL OVER NICKEL 50μ" MIN. PLATING
E	TIP SPRING	1	COPPER ALLOY, 0.25t	
D	RING-A	1	COPPER ALLOY, 0.2t	Au 50" ON CONTACT AREA, WHITE TIN 120μ" ON SOLDER TAIL, ALL OVER NICKEL 50μ" MIN. PLATING
C	RING-B	1	COPPER ALLOY, 0.2t	ALL OVER NICKEL 50μ" MIN. PLATING
B	EARTH	1	COPPER ALLOY, 0.2t	
A	BODY	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
Singatron Enterprise Co., Ltd. 信達企業股份有限公司				
UNLESS OTHERWISE SPECIFIED TOLERANCES				
DECIMALS:		ANGLES:		
X	:±0.5	X	:±2°	
X.X	:±0.3	X.X	:±1°	
X.XX	:±0.2			
TITLE: φ3.50 AUDIO JACK				
DWN	Julia	PART NO.	2S3082-060111F	
CHKD	Bruce	SCALE:4:1	UNIT:	mm
APVD	Lussen	SIZE: A3	SHEET:1 OF 1	REV: A
CUSTOMER COPY				

